

BINDER FOR THICK-FILM PASTE

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Abstract of JP10036479

PROBLEM TO BE SOLVED: To obtain a binder for thick-film pastes which remains no carbon even when baked in the atmosphere, a low-temperature range or an inert gas atmosphere by using a specified high-molecular compound having a specified average molecular weight or higher.
SOLUTION: A dihydroxy compound having an average molecular weight of 1,000 or above and obtained by the addition polymerization of an alkylene oxide is reacted with a dicarboxylic acid, its anhydride or its lower alkyl ester or reacted with an isocyanate-terminated compound to obtain an ester-bond- containing or a urethane-bond-containing polymer compound having an average molecular weight of 20,000 or above. It is desirable that the polymer compound has 50wt.% or above alkylene oxide. The polymer compound is used as a binder for thick-film pastes.

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